AB817D-B

Photocoupler

DESCRIPTIONS

- The AB817D-B (1-channel) is optically coupled isolators containing a GaAs Light Emitting Diode and an NPN silicon phototransistor
- The lead pitch is 2.54mm

FEATURES

- Lead forming (gull wing) type, for surface mounting
- High isolation voltage between input and output (Viso=5000 Vrms)
- Compact dual-in-line package AB817D-B:1-channel type
- Package: 1000 pcs / reel
- Moisture sensitivity level: 4
- RoHS compliant

APPLICATIONS

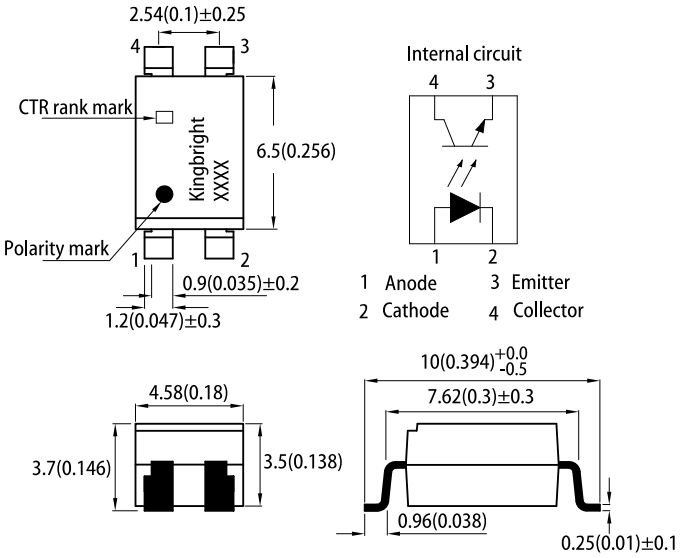
- Computer terminals
- Registers, copiers, automatic vending machines
- System appliances, measuring instruments
- Programmable logic controller
- Signal transmission between circuits of different potentials and impedances

NOTES ON HANDLING

Cautions regarding electrical noise

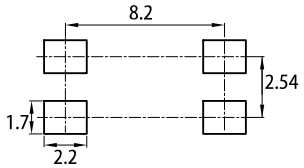
Please ensure the power supply is stable at all times. Even if the designed operating voltage is within specification limits, sudden voltage spikes at startup may damage the component.

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.15)



Notes:
1. *All dimensions are in millimeters (inches).*
2. *Tolerance is ±0.5(0.02") unless otherwise noted.*
3. *The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.*
4. *The device has a single mounting surface. The device must be mounted according to the specifications.*

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter			Symbol	Value			Units	Test Conditions
				Min.	Typ.	Max.		
Input	Forward voltage		V_F	-	1.2	1.4	V	I_F=20mA
	Peak forward voltage		V_{FM}	-	-	3.0	V	I_{FM}=0.5A
	Reverse current		I_R	-	-	10	μA	V_R=4V
Output	Collector dark current		I_{CEO}	-	-	10^{-7}	A	I_F=0mA,V_{CE}=20V
Transfer characteristics	Current transfer ratio [1]		CTR	300	-	600	%	I_F=5mA,V_{CE}=5V
	Collector-emitter saturation voltage		$V_{CE(sat)}$	-	0.1	0.2	V	I_F=20mA,I_C=1mA
	Cut-off frequency		f_c	-	80	-	kHz	V_{CE}=5V, I_C=2mA R_L=100 Ω,-3dB
	Response time	Rise time	t_r	-	4	18	μs	V_{CE}=2V, I_C=2mA R_L=100 Ω
		Fall time	t_f	-	3	18	μs	

Notes:
1.Classification table of current transfer ratio is shown below.
CTR=$\frac{I_C}{I_F}$ X 100%.
2.Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P_D	70	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	50	mA
	Collector power dissipation	P_C	150	mW
Total power dissipation		P_{tot}	200	mW
Isolation voltage [1]		V_{iso}	5000	Vrms
Operating temperature		T_{opr}	-30~+100	°C
Storage temperature		T_{stg}	-55~+125	°C

Notes:
1.40 to 60% RH,AC for 1 minute.
2.Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

Fig. 1 Current Transfer Ratio vs. Forward Current

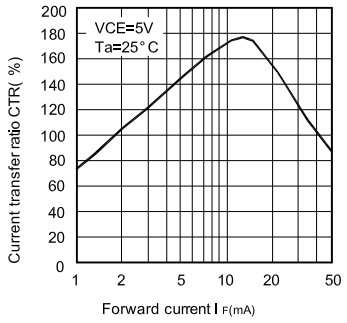


Fig. 2 Forward Current vs. Forward Voltage

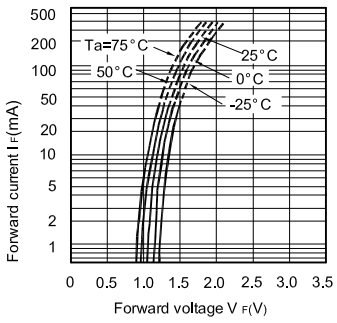


Fig. 3 Collector Current vs. Collector-Emitter Voltage

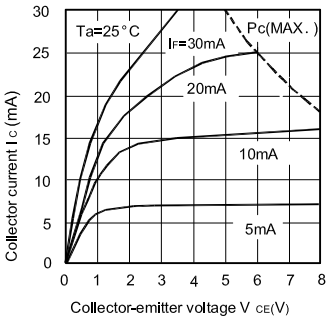


Fig. 4 Relative Current Transfer Ratio vs. Ambient Temperature

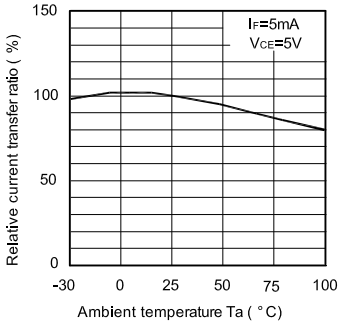


Fig. 5 Collector-Emitter Saturation Voltage vs. Ambient Temperature

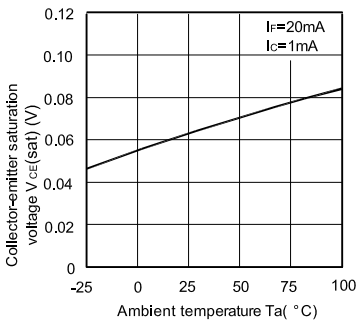


Fig. 6 Collector Dark Current vs. Ambient Temperature

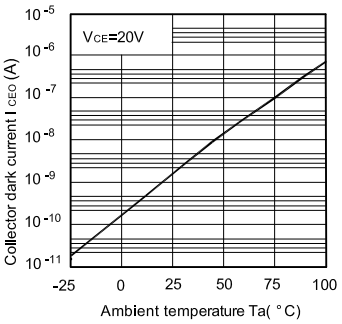


Fig. 7 Forward Current vs. Ambient Temperature

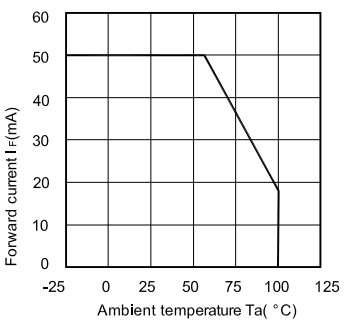


Fig. 8 Collector Power Dissipation vs. Ambient Temperature

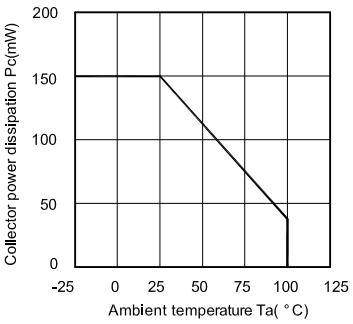


Fig. 9 Response Time vs. Load Resistance

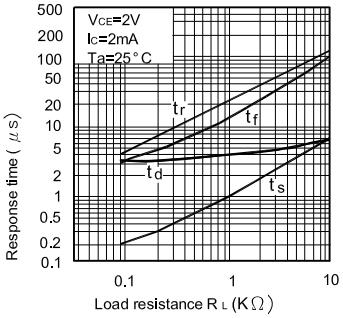


Fig.10 Frequency Response

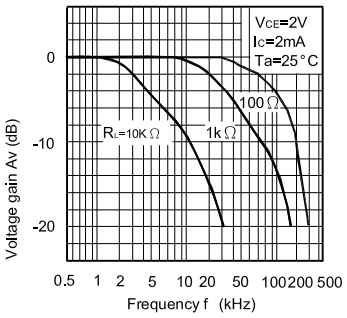
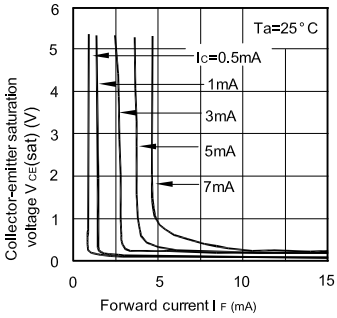
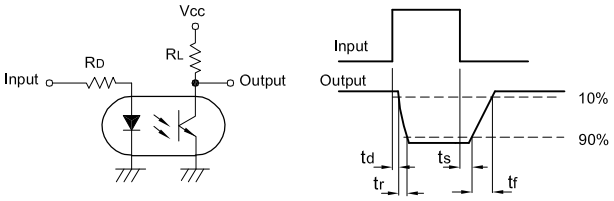


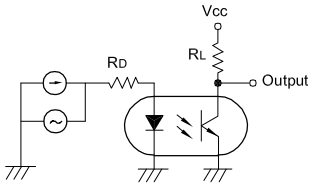
Fig.11 Collector-Emitter Saturation Voltage vs. Forward Current



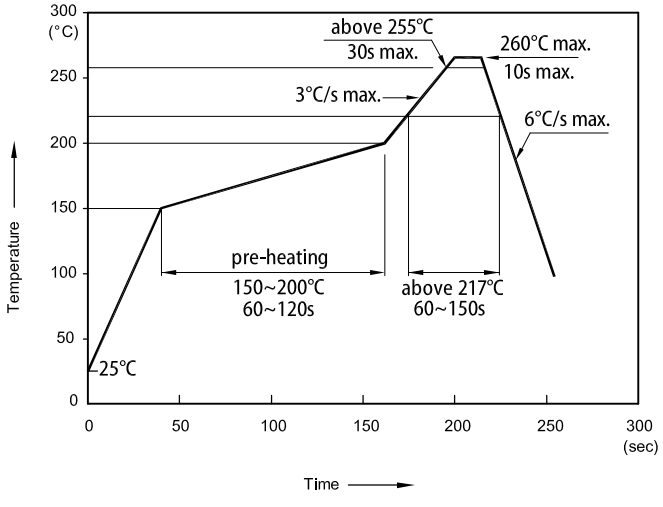
Test Circuit for Response Time



Test Circuit for Frequency Response

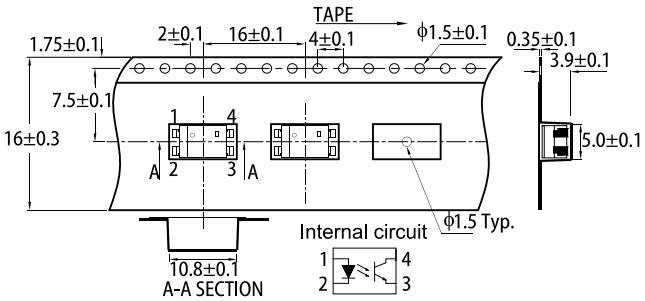


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

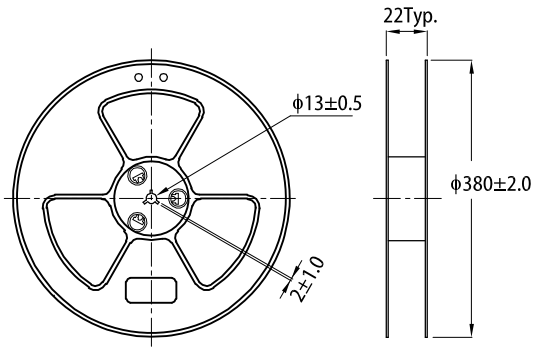


Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

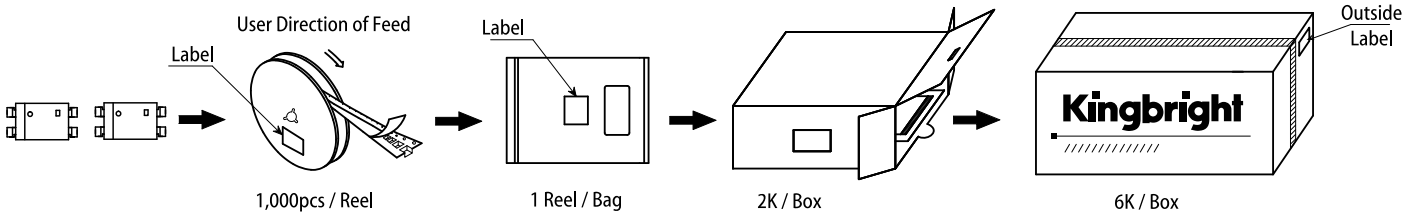
TAPE SPECIFICATIONS (units : mm)

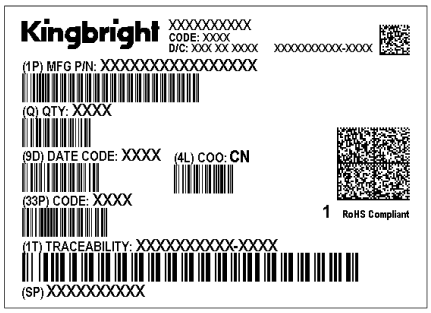


REEL DIMENSION (units : mm)



PACKING & LABEL SPECIFICATIONS





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